

ABSTRACT OF THE DISCLOSURE
METHOD FOR MANUFACTURING CONDUCTIVE WAFERS,
METHOD FOR MANUFACTURING THIN-PLATE SINTERED COMPACTS,
METHOD FOR MANUFACTURING CERAMIC SUBSTRATES
FOR THIN-FILM MAGNETIC HEAD, AND
METHOD FOR MACHINING CONDUCTIVE WAFERS

A method for manufacturing thin-plate sintered compacts according to the present invention includes the steps of: forming a conductive sintered compact to have such a thickness as to cause a warp to a negligible degree; and slicing the conductive sintered compact, thereby cutting and dividing the conductive sintered compact into at least two wafers.

(FIG. 3)



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